

# Surface Mount Schottky Power Rectifier Pb-Free package is available

The Schottky Power Rectifier employs the Schottky Barrier principle with a barrier metal that produces optimal forward voltage drop—reverse current tradeoff. Ideally suited for low voltage, high frequency rectification, or as a free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system. This package provides an alternative to the leadless 34 MELF style package.

#### **Features**

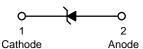
- Guardring for Stress Protection
- Very Low Forward Voltage
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Package Designed for Optimal Automated Board Assembly
- We declare that the material of product compliance with RoHS requirements.

#### **Mechanical Characteristics**

- Reel Options:LMBR0540T1G= 3,000 per 7 inch reel/8 mm tape LMBR0540T3G=10,000 per 13 inch reel/8 mm tape
- Device Marking: B4
- Polarity Designator: Cathode Band
- Weight: 11.7 mg (approximately)
- Case: Epoxy Molded
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C max. for 10 Seconds

# LMBR0540T1G







#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	40	V
Average Rectified Forward Current (At Rated V <sub>R</sub> , T <sub>C</sub> = 115°C)	Io	0.5	А
Peak Repetitive Forward Current (At Rated V <sub>R</sub> , Square Wave, 20 kHz, T <sub>C</sub> = 115°C)	I <sub>FRM</sub>	1.0	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	5.5	A
Storage/Operating Case Temperature Range	$T_{stg}$ , $T_{C}$	-55 to +150	°C
Operating Junction Temperature	TJ	-55 to +150	°C
Voltage Rate of Change (Rated V <sub>R</sub> , T <sub>J</sub> = 25°C)	dv/dt	1000	V/μs

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

## THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Resistance – Junction–to–Lead (Note 1) Thermal Resistance – Junction–to–Ambient (Note 2)	R <sub>tjl</sub> R <sub>tja</sub>	118 206	°C/W

#### **ELECTRICAL CHARACTERISTICS**

Maximum Instantaneous Forward Voltage (Note 3)	٧ <sub>F</sub>	T <sub>J</sub> = 25°C	T <sub>J</sub> = 100°C	V
$(i_F = 0.5 \text{ A})$ $(i_F = 1 \text{ A})$		0.55 0.65	0.53 0.63	
Maximum Instantaneous Reverse Current (Note 3)	I <sub>R</sub>	T <sub>J</sub> = 25°C	T <sub>J</sub> = 100°C	μΑ
$(V_R = 40 \text{ V})$ $(V_R = 20 \text{ V})$		20 10	13,000 5,000	

<sup>1.</sup> Mounted with minimum recommended pad size, PC Board FR4.

<sup>2. 1</sup> inch square pad size (1 X 0.5 inch for each lead) on FR4 board.

<sup>3.</sup> Pulse Test: Pulse Width  $\leq$  250  $\mu$ s, Duty Cycle  $\leq$  2.0%.



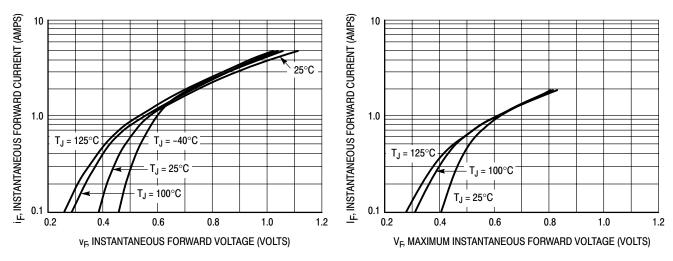


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage

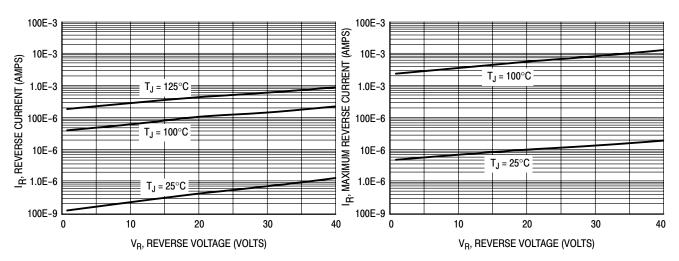
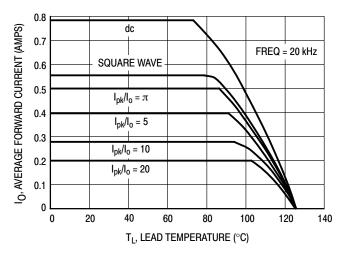


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

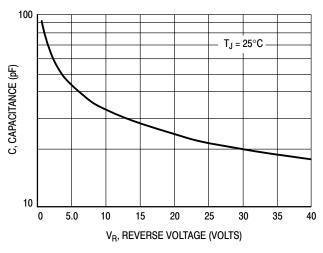




0.45 P<sub>FO</sub>, AVERAGE POWER DISSIPATION (WATTS) 0.40 SQUARE WAVE dc 0.35  $I_{pk}/I_0 = \pi$ 0.30  $I_{pk}/I_0 = 5$ 0.25  $I_{pk}/I_0 = 10$ 0.20  $I_{pk}/I_0 = 20$ 0.15 0.10 0.05 0.1 0.4 0.5 0.6 0.7 0.8 IO, AVERAGE FORWARD CURRENT (AMPS)

Figure 5. Current Derating

Figure 6. Forward Power Dissipation



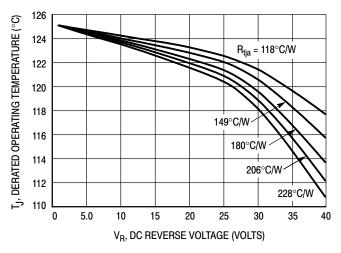


Figure 7. Capacitance

Figure 8. Typical Operating Temperature Derating\*

r(t) = thermal impedance under given conditions,

Pf = forward power dissipation, and

Pr = reverse power dissipation

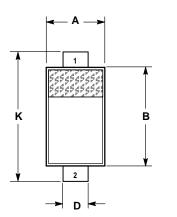
This graph displays the derated allowable  $T_J$  due to reverse bias under DC conditions only and is calculated as  $T_J = T_{Jmax} - r(t)Pr$ , where r(t) = Rthja. For other power applications further calculations must be performed.

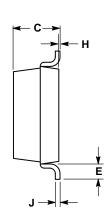
<sup>\*</sup> Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of  $T_J$  therefore must include forward and reverse power effects. The allowable operating  $T_J$  may be calculated from the equation:  $T_J = T_{Jmax} - r(t)(Pf + Pr)$  where



# **PACKAGE DIMENSIONS**

### SOD-123





#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.055	0.071	1.40	1.80	
В	0.100	0.112	2.55	2.85	
С	0.037	0.053	0.95	1.35	
D	0.020	0.028	0.50	0.70	
Е	0.004		0.25		
Н	0.000	0.004	0.00	0.10	
J		0.006		0.15	
K	0.140	0.152	3.55	3.85	

STYLE 1: PIN 1. CATHODE 2. ANODE

# **RECOMMENDED FOOTPRINT FOR SOD-123**

